

Title (en)
COPPER-NICKEL-SILICON ALLOYS

Title (de)
KUPFER-NICKEL-SILIZIUM-LEGIERUNGEN

Title (fr)
ALLIAGES DE CUIVRE-NICKEL-SILICIUM

Publication
EP 3158095 A1 20170426 (EN)

Application
EP 08864853 A 20081219

Priority

- US 1644107 P 20071221
- US 4490008 P 20080414
- US 33673108 A 20081217
- US 2008087705 W 20081219

Abstract (en)
[origin: WO2009082695A1] A copper base alloy having an improved combination of yield strength and electrical conductivity consisting essentially of between about 1.0 and about 6.0 weight percent Ni, up to about 3.0 weight percent Co, between about 0.5 and about 2.0 weight percent Si, between about 0.01 and about 0.5 weight percent Mg, up to about 1.0 weight percent Cr, up to about 1.0 weight percent Sn, and up to about 1.0 weight percent Mn, the balance being copper and impurities, the alloy processed to have a yield strength of at least about 137ksi, and an electrical conductivity of at least about 25% IACS.

IPC 8 full level
C22C 9/06 (2006.01); **C22C 9/10** (2006.01); **C22F 1/08** (2006.01)

CPC (source: EP US)
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